Lattice Semiconductor Corporation - LFXP10C-3FN388I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10000
Total RAM Bits	221184
Number of I/O	244
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp10c-3fn388i

Figure 2-10. PLL Diagram

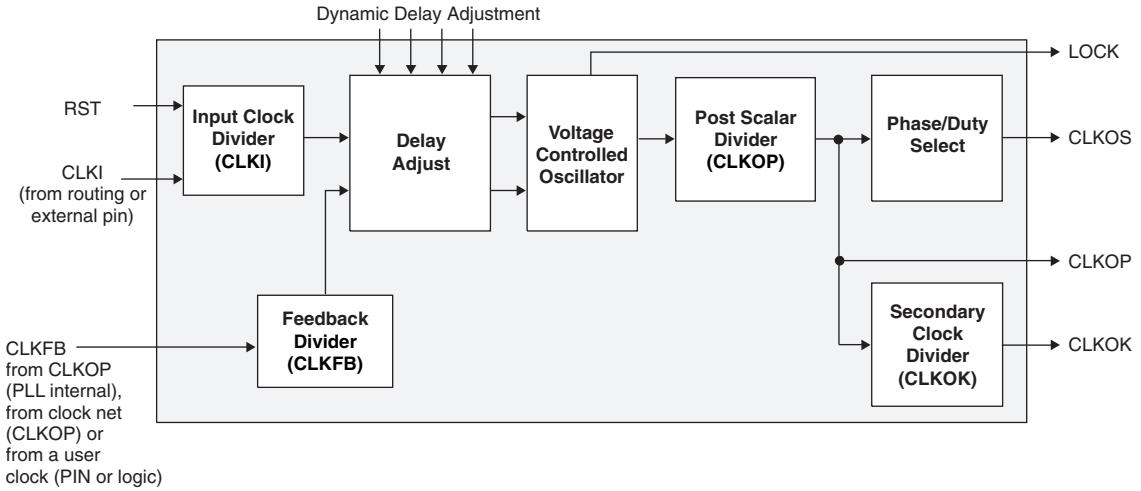


Figure 2-11 shows the available macros for the PLL. Table 2-11 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive

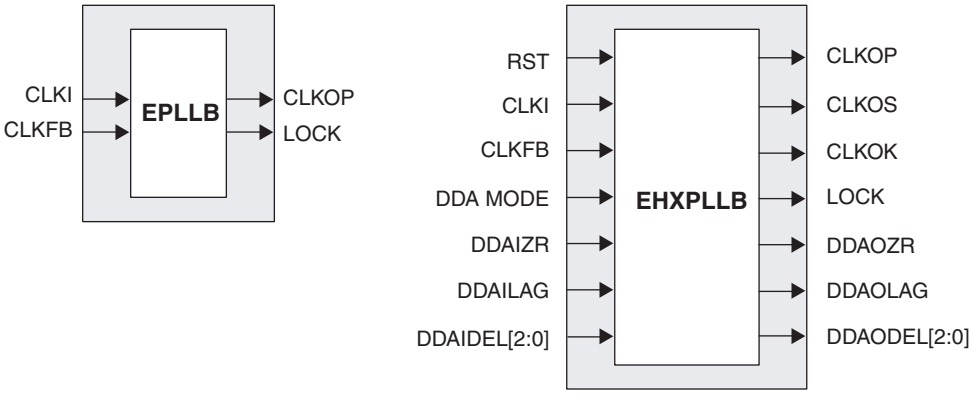


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	“1” to reset input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	“1” indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. “1” Pin control (dynamic), “0”: Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. “1”: delay = 0, “0”: delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. “1”: Lag, “0”: Lead
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

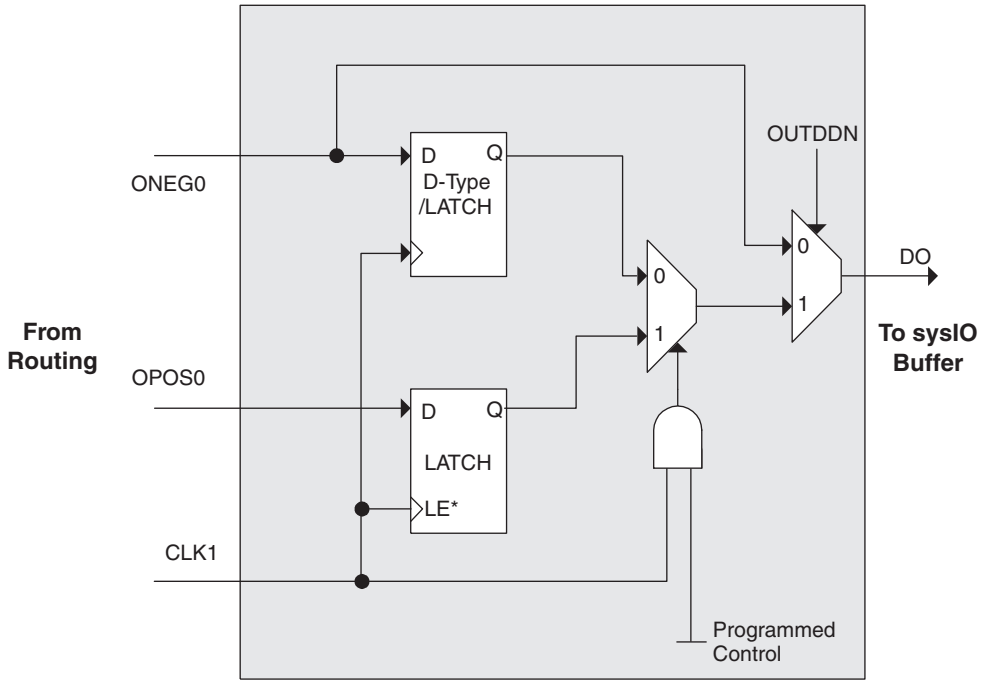
Memory Cascading

Larger and deeper blocks of RAMs can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

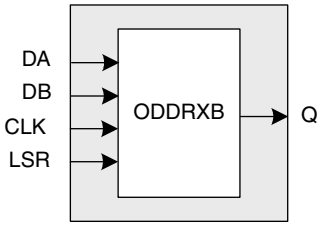
Figure 2-14 shows the four basic memory configurations and their input/output names. In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

Figure 2-23. Output Register Block



*Latch is transparent when input is low.

Figure 2-24. ODDRXB Primitive

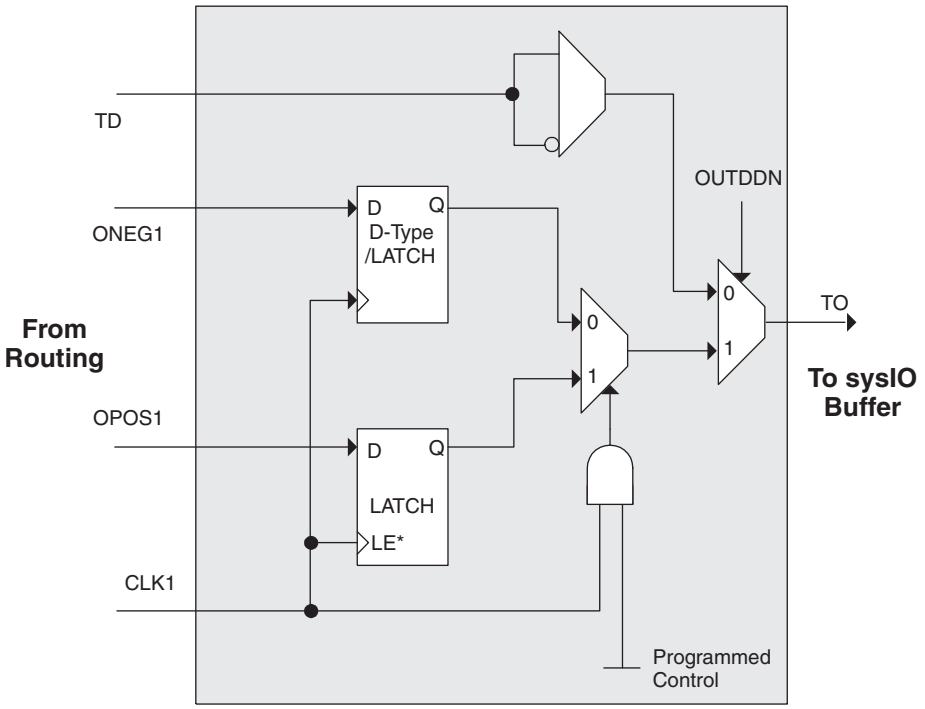


Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-25. Tristate Register Block



*Latch is transparent when input is low.

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2, 4]	Input or I/O Leakage	$0 \le V_{IN} \le (V_{CCIO} - 0.2V)$	—	—	10	µA
		$(V_{CCIO} - 0.2V) < V_{IN} \le 3.6V$	—	—	40	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance[3]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Not applicable to SLEEPN/TOE pin.
3. T_A 25°C, f = 1.0MHz
4. When V_{IH} is higher than V_{CCIO}, a transient current typically of 30ns in duration or less with a peak current of 6mA can be expected on the high-to-low transition.

Supply Current (Sleep Mode)[1, 2, 3]

Symbol	Parameter	Device	Typ.[4]	Max	Units
I_{CC}	Core Power Supply	LFXP3C	12	65	µA
		LFXP6C	14	75	µA
		LFXP10C	16	85	µA
		LFXP15C	18	95	µA
		LFXP20C	20	105	µA
I_{CCP}	PLL Power Supply (per PLL)	All LFXP 'C' Devices	1	5	µA
I_{CCAUX}	Auxiliary Power Supply	LFXP3C	2	90	µA
		LFXP6C	2	100	µA
		LFXP10C	2	110	µA
		LFXP15C	3	120	µA
		LFXP20C	4	130	µA
I_{CCIO}	Bank Power Supply[5]	LFXP3C	2	20	µA
		LFXP6C	2	22	µA
		LFXP10C	2	24	µA
		LFXP15C	3	27	µA
		LFXP20C	4	30	µA
I_{CCJ}	VCCJ Power Supply	All LFXP 'C' Devices	1	5	µA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.
2. Frequency 0MHz.
3. User pattern: blank.
4. T_A=25°C, power supplies at nominal voltage.
5. Per bank.

Initialization Supply Current[1, 2, 3, 4, 5, 6]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[7]	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.
2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. Typical user pattern.
6. Assume normal bypass capacitor/decoupling capacitor across the supply.
7. T_A=25°C, power supplies at nominal voltage.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

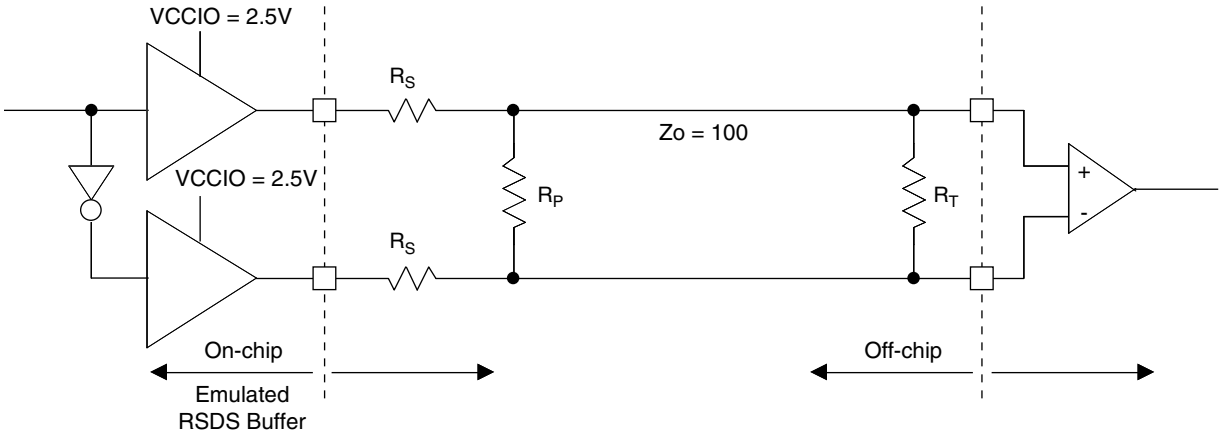
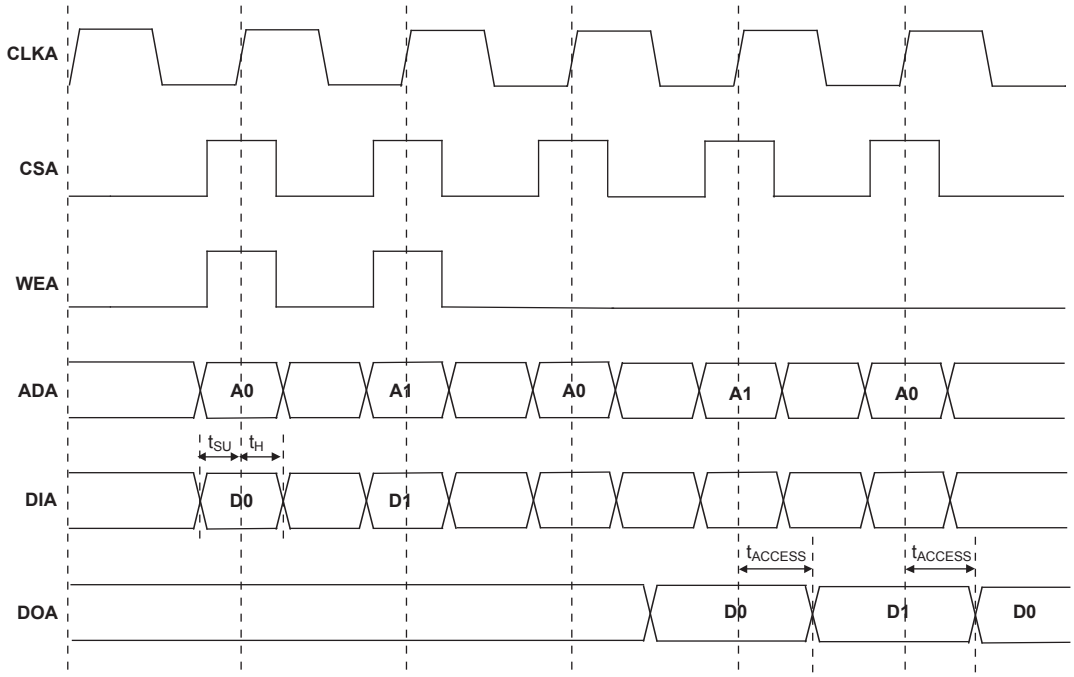


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohms
R_S	Driver series resistor	300	ohms
R_P	Driver parallel resistor	121	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohms
I_{DC}	DC output current	3.66	mA

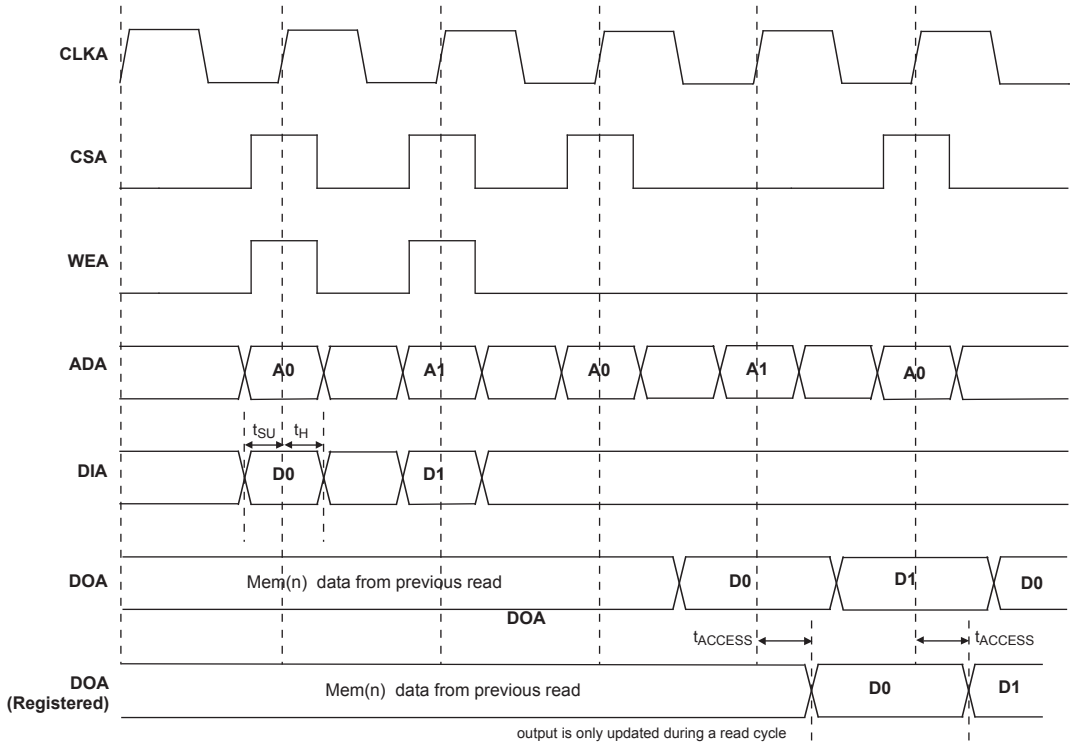
EBR Memory Timing Diagrams

Figure 3-8. Read Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-9. Read Mode with Input and Output Registers



Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

Pin Information Summary[1] (Cont.)

Pin Type		XP10		XP15			XP20		
		256 fpBGA	388 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA
Single Ended User I/O		188	244	188	268	300	188	268	340
Differential Pair User I/O[2]		76	104	76	112	128	76	112	144
Configuration	Dedicated	11	11	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14	14	14
TAP		5	5	5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6	6	6
V_{CC}		8	14	8	14	28	8	14	28
V_{CCAUX}		4	4	4	4	12	4	4	12
V_{CCPLL}		2	2	2	2	2	2	2	2
V_{CCIO}	Bank0	2	5	2	5	4	2	5	4
	Bank1	2	5	2	5	4	2	5	4
	Bank2	2	4	2	4	4	2	4	4
	Bank3	2	4	2	4	4	2	4	4
	Bank4	2	5	2	5	4	2	5	4
	Bank5	2	5	2	5	4	2	5	4
	Bank6	2	4	2	4	4	2	4	4
	Bank7	2	4	2	4	4	2	4	4
GND		24	50	24	50	56	24	50	56
GND_{PLL}		2	2	2	2	2	2	2	2
NC		0	24	0	0	40	0	0	0
Single Ended/ Differential I/O per Bank[2]	Bank0	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank1	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank2	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank3	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank4	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank5	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank6	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank7	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
V_{CCJ}		1	1	1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PT6A	0	-	DI	PT9A	0	-	DI
140	PT5A	0	-	CSN	PT8A	0	-	CSN
141	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
142	CFG0	0	-	-	CFG0	0	-	-
143	CFG1	0	-	-	CFG1	0	-	-
144	DONE	0	-	-	DONE	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L15	PR21B	3	C[3]	-	PR28B	3	C[3]	-
L14	PR21A	3	T[3]	-	PR28A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L12	PR17B	3	C	-	PR26A	3	-	-
M16	PR20B	3	C	-	PR25B	3	C	RLM0_PLLC_IN_A
N16	PR20A	3	T	-	PR25A	3	T	RLM0_PLLT_IN_A
K14	PR19B	3	C[3]	-	PR24B	3	C[3]	-
K15	PR19A	3	T[3]	-	PR24A	3	T[3]	DQS
K12	PR17A	3	T	-	PR23B	3	-	-
K13	PR22A	3	-	VREF2_3	PR22A	3	-	VREF2_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L16	PR18B	3	C[3]	-	PR21B	3	C[3]	-
K16	PR18A	3	T[3]	-	PR21A	3	T[3]	-
J15	PR16B	3	C[3]	-	PR19B	3	C[3]	-
J14	PR16A	3	T[3]	-	PR19A	3	T[3]	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR12B	2	C	PCLKC2_0	PR17B	2	C	PCLKC2_0
H16	PR12A	2	T	PCLKT2_0	PR17A	2	T	PCLKT2_0
H13	PR13B	2	C[3]	-	PR16B	2	C[3]	-
H12	PR13A	2	T[3]	-	PR16A	2	T[3]	DQS
H15	PR2B	2	C[3]	-	PR15B	2	-	-
H14	PR6B	2	-	VREF1_2	PR14A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR11B	2	C[3]	-	PR13B	2	C[3]	-
G14	PR11A	2	T[3]	-	PR13A	2	T[3]	-
G16	PR8B	2	C	RUM0_PLLC_IN_A	PR12B	2	C	RUM0_PLLC_IN_A
F16	PR8A	2	T	RUM0_PLLT_IN_A	PR12A	2	T	RUM0_PLLT_IN_A
G13	PR2A	2	T[3]	-	PR11B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR9B	2	C[3]	-	PR8B	2	C	-
F13	PR9A	2	T[3]	-	PR8A	2	T	-
B16	PR7B	2	C[3]	-	PR7B	2	C[3]	-
C16	PR7A	2	T[3]	DQS	PR7A	2	T[3]	DQS
F15	PR14A	2	-	-	PR6B	2	-	-
E15	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F14	PR4B	2	C[3]	-	PR4B	2	C[3]	-
E14	PR4A	2	T[3]	-	PR4A	2	T[3]	-
D15	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
C15	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
P16	PR37B	3	C[3]	-	PR41B	3	C[3]	-
R16	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
M15	PR36B	3	-	-	PR40B	3	-	-
N14	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR33B	3	C	-	PR37B	3	C	-
L13	PR33A	3	T	-	PR37A	3	T	-
L15	PR32B	3	C[3]	-	PR36B	3	C[3]	-
L14	PR32A	3	T[3]	-	PR36A	3	T[3]	-
L12	PR30A	3	-	-	PR34A	3	-	-
M16	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
N16	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
K14	PR28B	3	C[3]	-	PR32B	3	C[3]	-
K15	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
K12	PR27B	3	-	-	PR31B	3	-	-
K13	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
L16	PR25B	3	C[3]	-	PR29B	3	C[3]	-
K16	PR25A	3	T[3]	-	PR29A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
J15	PR23B	3	C[3]	-	PR27B	3	C[3]	-
J14	PR23A	3	T[3]	-	PR27A	3	T[3]	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
H16	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
H13	PR20B	2	C[3]	-	PR20B	2	C[3]	-
H12	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
H15	PR19B	2	-	-	PR19B	2	-	-
H14	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR17B	2	C[3]	-	PR17B	2	C[3]	-
G14	PR17A	2	T[3]	-	PR17A	2	T[3]	-
G16	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
F16	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
G13	PR15B	2	-	-	PR15B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR12B	2	C	-	PR12B	2	C	-
F13	PR12A	2	T	-	PR12A	2	T	-
B16	PR11B	2	C[3]	-	PR11B	2	C[3]	-
C16	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
U1	PL25A	6	T	LLM0_PLLT_IN_A	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
T2	PL25B	6	C	LLM0_PLLC_IN_A	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
V1	PL26A	6	T[3]	-	PL30A	6	T[3]	-	PL34A	6	T[3]	-
U2	PL26B	6	C[3]	-	PL30B	6	C[3]	-	PL34B	6	C[3]	-
W1	PL28A	6	T[3]	-	PL32A	6	T[3]	-	PL36A	6	T[3]	-
V2	PL28B	6	C[3]	-	PL32B	6	C[3]	-	PL36B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	-	-	-	GNDIO6	6	-	-
P3	PL29A	6	T	-	PL33A	6	T	-	PL37A	6	T	-
P4	PL29B	6	C	-	PL33B	6	C	-	PL37B	6	C	-
Y1	PL30A	6	T[3]	-	PL34A	6	T[3]	-	PL38A	6	T[3]	-
W2	PL30B	6	C[3]	-	PL34B	6	C[3]	-	PL38B	6	C[3]	-
R3	PL31A	6	-	VREF2_6	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL32B	6	-	-	PL36B	6	-	-	PL40B	6	-	-
T3	PL33A	6	T[3]	DQS	PL37A	6	T[3]	DQS	PL41A	6	T[3]	DQS
T4	PL33B	6	C[3]	-	PL37B	6	C[3]	-	PL41B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
V4	PL34A	6	T	LLM0_PLLT_FB_A	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
V3	PL34B	6	C	LLM0_PLLC_FB_A	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
U4	PL35A	6	T[3]	-	PL39A	6	T[3]	-	PL43A	6	T[3]	-
U3	PL35B	6	C[3]	-	PL39B	6	C[3]	-	PL43B	6	C[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-	GNDIO6	6	-	-
W5	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
Y2	INITN	5	-	-	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y3	-	-	-	-	PB3B	5	-	-	PB7B	5	-	-
W3	-	-	-	-	PB4A	5	T	-	PB8A	5	T	-
W4	-	-	-	-	PB4B	5	C	-	PB8B	5	C	-
AA2	-	-	-	-	PB5A	5	-	-	PB9A	5	-	-
AA1	-	-	-	-	PB6B	5	-	-	PB10B	5	-	-
W6	PB2A	5	-	-	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	-	-	-	-	PB7B	5	C	-	PB11B	5	C	-
Y4	PB3A	5	T	-	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y5	PB3B	5	C	-	PB8B	5	C	-	PB12B	5	C	-
AB2	PB4A	5	T	-	PB9A	5	T	-	PB13A	5	T	-
AA3	PB4B	5	C	-	PB9B	5	C	-	PB13B	5	C	-
AB3	PB5A	5	T	-	PB10A	5	T	-	PB14A	5	T	-
AA4	PB5B	5	C	-	PB10B	5	C	-	PB14B	5	C	-
W8	PB6A	5	T	-	PB11A	5	T	-	PB15A	5	T	-
W9	PB6B	5	C	-	PB11B	5	C	-	PB15B	5	C	-
AB4	PB7A	5	T	VREF1_5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB7B	5	C	-	PB12B	5	C	-	PB16B	5	C	-
AB5	PB8A	5	-	-	PB13A	5	-	-	PB17A	5	-	-
Y6	PB9B	5	-	-	PB14B	5	-	-	PB18B	5	-	-
AA6	PB10A	5	T	DQS	PB15A	5	T	DQS	PB19A	5	T	DQS
AB6	PB10B	5	C	-	PB15B	5	C	-	PB19B	5	C	-
Y9	PB11A	5	T	-	PB16A	5	T	-	PB20A	5	T	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
H13	VCCIO1	1	-	-	VCCIO1	1	-	-
K15	VCCIO2	2	-	-	VCCIO2	2	-	-
L15	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-
L17	VCCIO2	2	-	-	VCCIO2	2	-	-
M15	VCCIO3	3	-	-	VCCIO3	3	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-
M17	VCCIO3	3	-	-	VCCIO3	3	-	-
N15	VCCIO3	3	-	-	VCCIO3	3	-	-
R12	VCCIO4	4	-	-	VCCIO4	4	-	-
R13	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-
U12	VCCIO4	4	-	-	VCCIO4	4	-	-
R10	VCCIO5	5	-	-	VCCIO5	5	-	-
R11	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-
U11	VCCIO5	5	-	-	VCCIO5	5	-	-
M6	VCCIO6	6	-	-	VCCIO6	6	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-
M8	VCCIO6	6	-	-	VCCIO6	6	-	-
N8	VCCIO6	6	-	-	VCCIO6	6	-	-
K8	VCCIO7	7	-	-	VCCIO7	7	-	-
L6	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-
L8	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4F256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5F256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3Q208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4Q208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5Q208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3T144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4T144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5T144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4F388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5F388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3F256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4F256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5F256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4F484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5F484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3F388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4F388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5F388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3F256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4F256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5F256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4F484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5F484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3F388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4F388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5F388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3F256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4F256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5F256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4Q208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3T100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4T100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3Q208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4Q208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4F388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484I	300	1.8/2.5/3.3V	-3	fpBGA	484	IND	15.5K
LFXP15C-4F484I	300	1.8/2.5/3.3V	-4	fpBGA	484	IND	15.5K
LFXP15C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	15.5K
LFXP15C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	15.5K
LFXP15C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	15.5K
LFXP15C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484I	340	1.8/2.5/3.3V	-3	fpBGA	484	IND	19.7K
LFXP20C-4F484I	340	1.8/2.5/3.3V	-4	fpBGA	484	IND	19.7K
LFXP20C-3F388I	268	1.8/2.5/3.3V	-3	fpBGA	388	IND	19.7K
LFXP20C-4F388I	268	1.8/2.5/3.3V	-4	fpBGA	388	IND	19.7K
LFXP20C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	19.7K
LFXP20C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208I	136	1.2V	-3	PQFP	208	IND	3.1K
LFXP3E-4Q208I	136	1.2V	-4	PQFP	208	IND	3.1K
LFXP3E-3T144I	100	1.2V	-3	TQFP	144	IND	3.1K
LFXP3E-4T144I	100	1.2V	-4	TQFP	144	IND	3.1K
LFXP3E-3T100I	62	1.2V	-3	TQFP	100	IND	3.1K
LFXP3E-4T100I	62	1.2V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256I	188	1.2V	-3	fpBGA	256	IND	5.8K
LFXP6E-4F256I	188	1.2V	-4	fpBGA	256	IND	5.8K
LFXP6E-3Q208I	142	1.2V	-3	PQFP	208	IND	5.8K
LFXP6E-4Q208I	142	1.2V	-4	PQFP	208	IND	5.8K
LFXP6E-3T144I	100	1.2V	-3	TQFP	144	IND	5.8K
LFXP6E-4T144I	100	1.2V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4F388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3F256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4F256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3FN484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4FN484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5FN484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3FN388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4FN388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5FN388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3FN256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4FN256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5FN256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3QN208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4QN208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5QN208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3TN144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4TN144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5TN144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3TN100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4TN100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5TN100C	62	1.2V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3FN256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4FN256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5FN256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3QN208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4QN208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5QN208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3TN144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4TN144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5TN144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4FN388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5FN388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3FN256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4FN256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5FN256C	188	1.2V	-5	fpBGA	256	COM	9.7K